

A1
CONT.

14. (Amended) The device according to claim 1 wherein the interface comprises turns of conductive material and the width of the turns around the microcircuit are thinner than elsewhere in such a way as to directly connect the microcircuit to ends of the interface with a small length of connecting wire.

Sub
B1

48. (New) The chip card of claim 26 wherein the support film and the interface can be folded with a radius of curvature less than 2.5 mm without deterioration.

Sub
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48. (New) The chip card of claim 48, wherein said radius of curvature is less than 1 mm.

50. (New) The chip card of claim 26 wherein said support film has a thickness less than 75 μm .

A2

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B1

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51. (New) The chip card of claim 50 wherein said support film has a thickness between 10 μm and 30 μm .

52. (New) The chip card of claim 26 wherein the support film has at least one of an elongation at break of more than 80%, a Shore hardness of less than 80, a vitreous transition temperature T_g of less than 0°, and a fusion temperature of less than 130°C.

Sub
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A

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(New) A chip card comprising a card body on which an electronic chip device is fixed, the card body having an area greater than or equal to that of the device, said electronic chip device comprising an interface support film including a support film and at least one flat communication interface formed by plural turns of a conductive material on the support film, said interface support film having such properties that it is capable of being folded over onto itself with a radius of curvature less than 2.5 mm without deterioration, and a microcircuit connected to the interface.

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(New) The chip card of claim ~~53~~³³, wherein said radius of curvature is less than 1 mm.

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(New) The chip card of claim ~~53~~³³, wherein said support film has a thickness less than 75 μm .

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(New) The chip card of claim ~~55~~³⁶, wherein said support film has a thickness between 10 μm and 30 μm .

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(New) The chip card of claim ~~53~~³³, wherein the support film has at least one of an elongation at break of more than 80%, a Shore hardness of less than 80, a vitreous transition temperature T_g of less than 0°, and a fusion temperature of less than 130°C.

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~~58~~³³ (New) The chip card of claim ~~53~~³³, further including a compensation film on the interface support film, said compensation film having a recess containing said microcircuit, its connections and an encapsulating material.

~~59~~³³ (New) The chip card of claim ~~53~~³³, wherein said microcircuit is disposed on said support sheet outside of said turns.

A2
cont.

60. (New) An electronic chip device comprising an interface support film including a support film and at least one communication interface formed by plural turns of a conductive material on the support film, a microcircuit connected to the interface, and a compensation film on the support film, said compensation film having a recess containing said microcircuit, its connections and an encapsulating material.

~~61~~⁴¹ (New) The device according to claim ~~60~~⁴⁰ wherein the support film has a thickness of less than 75 μm .

~~62~~⁴² (New) The device according to claim ~~61~~⁴¹ wherein the support film has a thickness between 10 μm and 30 μm .

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~~63~~. (New) The device according to claim ⁴⁰~~60~~, wherein the support film has at least one of an elongation at break of more than 80%, a Shore hardness of less than 80, a vitreous transition temperature Tg of less than 0°, and a fusion temperature of less than 130°C.

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~~64~~. (New) The device according to claim ⁴⁰~~60~~, wherein said microcircuit is disposed on said support sheet outside of said turns.

Kindly cancel claims 31-47.